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## **SPECIFICATION FOR APPROVAL**

DESCRIPTION: 1.25mm PITCH WIRE TO BOARD SMT CONNECTOR

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CUSTOMER PROD.NO/DWG.NO:

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E&T PROD.NO: 3806X-XXXX-04,06X

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APPROVAL SHEET NO:

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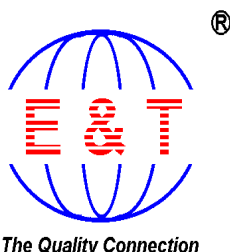
E&T DWG. NO./DOCUMENT: 3806X-XXXX-04,06X

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REV: A4

**PLEASE RETURN TO US ONE COPY OF "SPECIFICATION  
FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.**


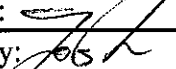
<b>APPROVED SIGNATURES</b>			



**ENTERY INDUSTRIAL CO., LTD.  
E&T ELECTRONICS (DONG GUAN) CO., LTD.  
E&T ELECTRONICS (SU ZHOU) CO., LTD.  
E&T ELECTRONICS (NANKEEN) CO., LTD.**

# ENTERY INDUSTRIAL CO., LTD.

**Title : 1.25mm WIRE TO BOARD  
SMT, R/A TYPE SINGLE ROW**

<b>Release History</b>		<b>Title: Pitch 1.25mm Wire To Board Connector, R/A, SMT Type Single Row.</b>	
<b>A4</b>	2012/09/13	This Document Contains Information That Is Proprietary To E&T And Should Not Be Used Without Written Permission	
<b>Rev</b>	<b>Description</b>		
Document No.		Prepared By: Well Liu	Date: 08,30,2010'
3806X-XXXX-04,06X		Checked By: 	Date: 09-20-2012
		Approved By: 	Date:

**ENTERY INDUSTRIAL CO., LTD.**

## GROUP AND TEST SEQUENCE

[illegible]

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## PRODUCT SPECIFICATION

### 1. SCOPE :

This specification covers the pitch 1.25 mm WIRE TO BOARD SMT connector series.

### 2. PRODUCT NAME AND PART NUMBER :

Product Name	E&T Part Number
1.25mm WIRE TO BOARD Connector, R/A, SMT Type Single Row	3806X-XXXX-04,06X

### 3. RATINGS :

Item	Standard	
Rated Voltage (MAX.)	125 V	AC(rms)/DC
Rated Current (MAX.)	1 A	
Operating Temperature Range	-40 <sup>0</sup> C ~ +85 <sup>0</sup> C*	

\*Including terminal temperature rise

### 4.PERFORMANCE :

#### 4- 1 Electrical Performance

Item		Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 10 mA . Test Voltage: 20mV Max Test Method: JIS C5402 5.4	20 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 500V DC. Test Method: MIL-STD-202, method 302	100 MΩ Min.
4-1-3	Dielectric Strength	Test Voltage: 500 V AC(rms). Test Time: 60 sec. Test Method: MIL-STD-202, Method 301.	No Breakdown

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## 4-2 Mechanical Performance

Item		Test Condition	Requirement	
4-2-1	Insertion and Withdrawal Force	Test Speed: 25±3 mm/min.	Insertion Force	0.22 kgf/PIN MAX.
			Withdrawal Force	0.02 kgf/PIN Min.
4-2-2	Pin Retention Force	Test Speed: 25±3mm/min.	0.2 kgf (Min)	
4-2-3	Locking Force ( For Lock Type )	Test Speed: 25±3 mm/min.	2kgf (Min)	

## 4-3 Environmental Performance and Others

Item		Test Condition	Requirement	
4-3-1	Durability	Insert and withdraw actuator up to 30cycles at the speed rate of less than 10 cycles/ minute.	Contact Resistance	
			Initial Value	≤ 20 mΩ
			Final Value	≤ 40 mΩ
4-3-2	Vibration	Amplitude : 1.5 mm P-P Frequency range: 10~55~10 Hz in 1 minute Duration: 2 hours in each X.Y.Z axes Test Method: MIL-STD-202F, Method 201	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
			Discontinuity	1μsec MAX
4-3-3	Heat Resistance	Temperature: 85±2℃ Duration: 96 hours Test Method: MIL-STD-202, Method 108.	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
4-3-4	Cold Resistance	Temperature: -40±3℃ Duration: 96 hours Test Method: JIS C60068-2-1	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
4-3-5	Humidity	Temperature: 60±2℃ Relative Humidity: 90~95% Duration: 96 hours Test Method: MIL-STD-202F , Method 103	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
			Insulation Resistance	≥ 10MΩ
			Dielectric Strength	Must meet 4-1-3

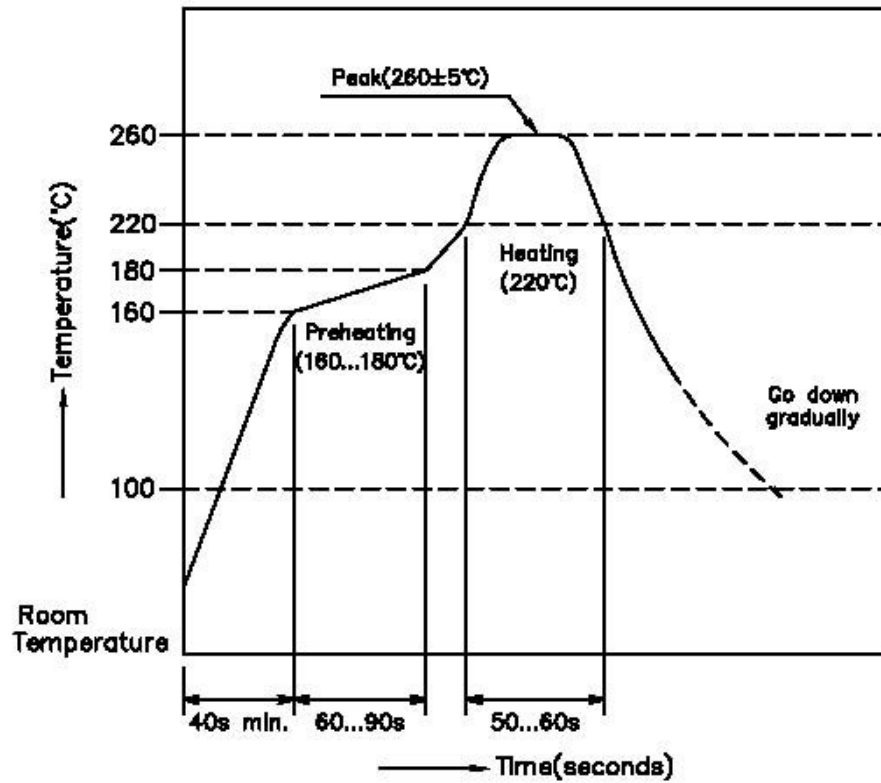
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Item		Test Condition	Requirement	
4-3-6	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5℃ Test Method: MIL-STD-202F , Method 208	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-7	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5℃ Test Method: MIL-STD-202F , Method 210A	Appearance	No Damage
4-3-8	Steam Aging	Steam Aging Temperature : 98±2℃ Duration: 8 hours Solder Temperature : 235±5℃ Soldering Time : 3±0.5 sec Test Method: MIL-STD-202F , Method 208	Appearance	No Damage
			Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-9	Salt Spray	Chamber Temperature : 35±2℃ Air Tank Temperature : 47±1℃ Salt Solution : 5 ± 1% Duration : 48 hours Test Method: MIL-STD-202 , Method 101D	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
4-3-10	Temperature Cycling	5 cycles of : a) - 55 ±3℃      30 minutes b) +105 ±3℃      30 minutes Test Method: JIS C0025	Appearance	No Damage
			Contact Resistance	≤ 40 mΩ
4-3-11	Temperature Rise Test	Carrying rated current load.	Temperature Rise : 30 °C (MAX)	

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## INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



## Wire To Board Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

### 1. Common Handling Precautions

- Do not expose E&T's wire to board connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's wire to board connector, processing process product and processing product . Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.
- E&T's wire to board connector is not designed for the mating and unmating of the connectors to be performed under the condition of an active electrical circuit. It may cause a spark and product defect if the connectors are mated and unmated in this way.

### 2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).
- Changing recommended pattern causes problems.

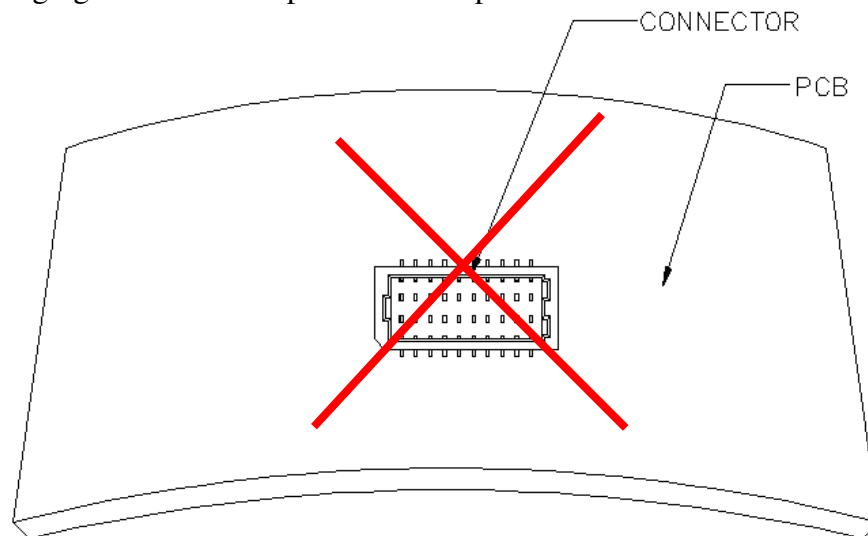


Figure 1.



## 3. Precautions Crimped Terminal Insertion

- Terminal must be inserted horizontally oriented (see figure 2).
- Do not attempt to insert crimped terminal in any other direction. (see figure 2).

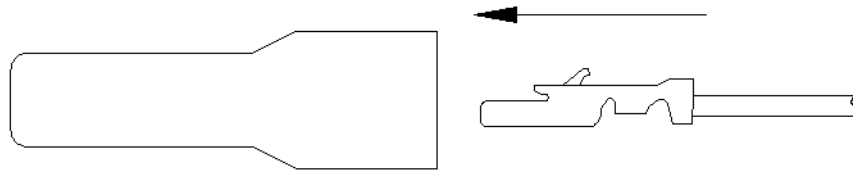


Figure 2.

## 4. Precautions When Inserting or Withdrawal Wire To Board

- Do not insert and remove at an angle of 25° or greater. Doing so will cause contact deformation or case damage. (see figure 3).
- Push the wire side connector until firmly closed. At this time, confirm that the wire side connector is mated securely.
- When mounting of connectors, its slant or aberration shall be 3° max.
- Do not insert and remove the connectors when the board side connector is not mounted on the PC board.
- Used Lock type, when removed to connectors, please released positive locks.

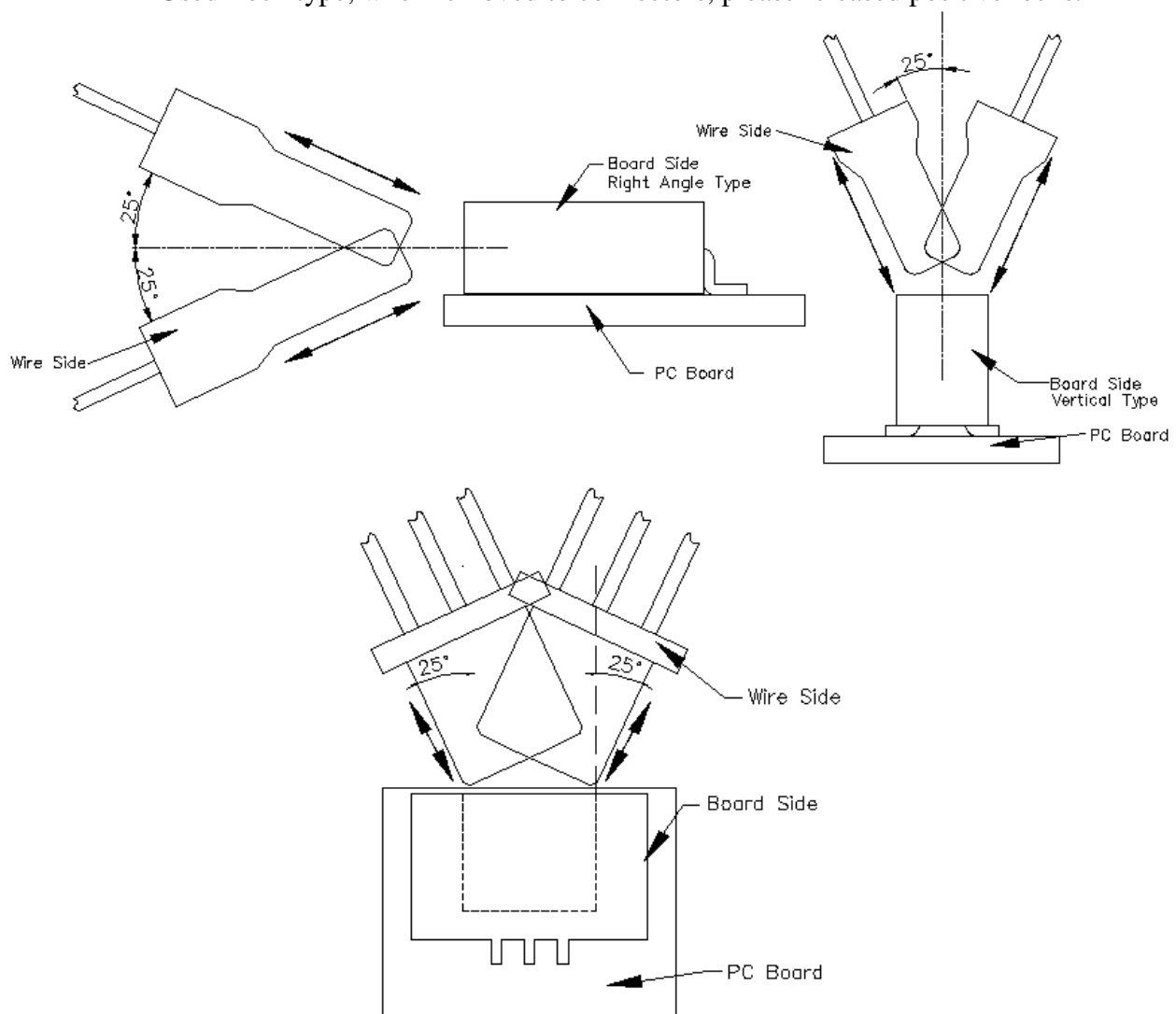


Figure 3.

## 5. Precautions Cable Assembly

- The cable assembly should not have a constant stress or pulling force applied on it when it is in the mated condition. Therefore, when designing the wire positioning, please ensure that there is enough length of wire to avoid stress on the connector. (see figure 4).

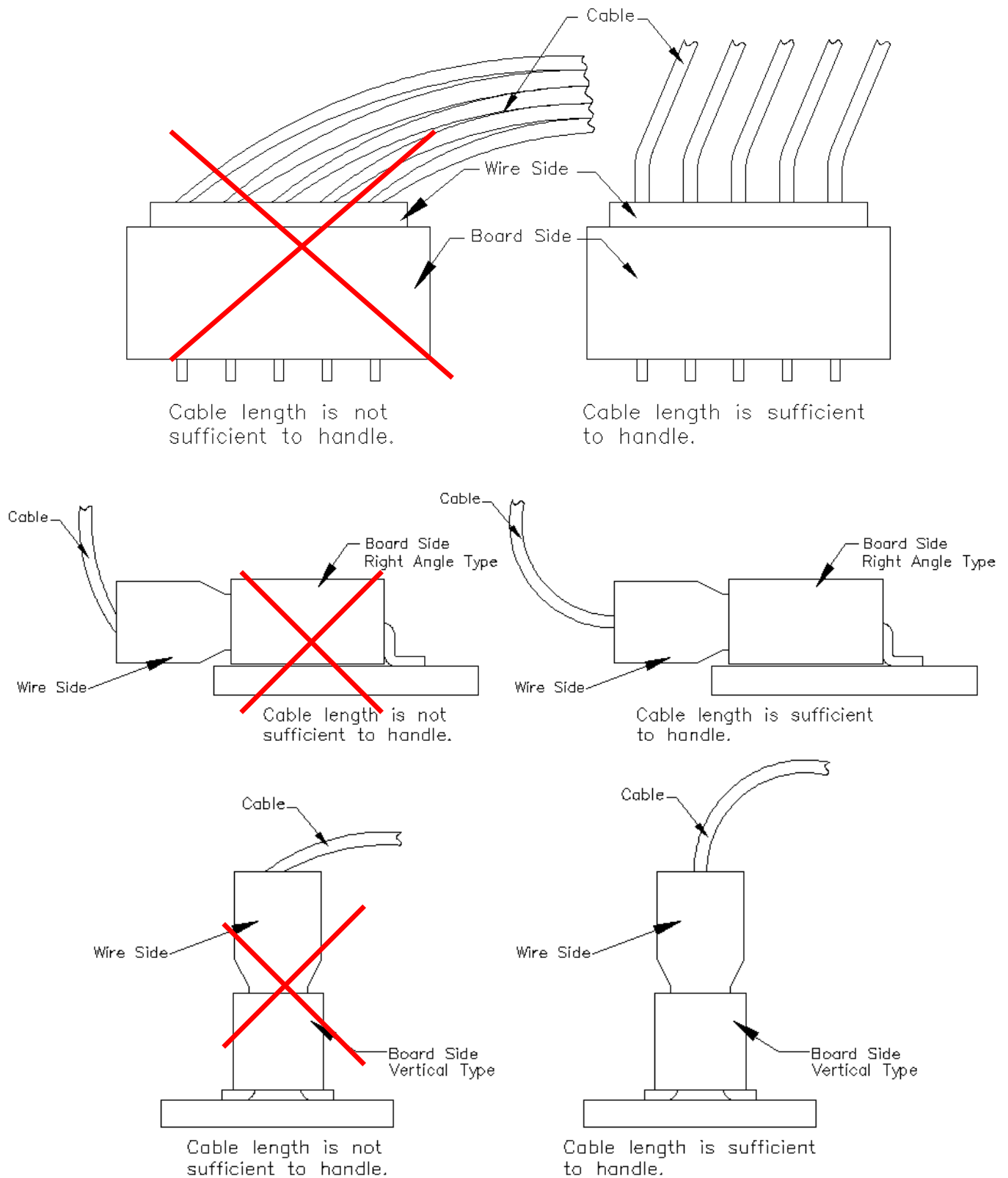


Figure 4.

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## RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A2	RE201110012 RE201111028	OCT-26-2011	KAZ	ADD Handling Precautions Cancel Packaging Spec
A3	DCN120507	MAY-24-2012	KAZ	ADD 06 TYPE
A4	RE201209003	SEP-13-2012	JIMMY	lot number intergration